

Housing wall e.g. for data processor housing, comprises non overlapping recesses in two transparent plates

Patent Number: DE10050326

Publication date: 2002-05-02

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Requested Patent: DE10050326

Application Number: DE20001050326 20001010

Priority Number(s): DE20001050326 20001010

IPC Classification: H05K7/20; H05K5/02; G06F1/20

EC Classification: G06F1/20, G06F1/18E, H05K5/02D

Equivalents:

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Abstract

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The housing wall for a housing (6) has a first plate or panel (1) and a second plate or panel (2). The panels are preferably transparent and are spaced apart one behind the other. Each plate has several recesses (4,5).

The panels are arranged such that the recesses (4) of the first panel (1) do not overlap with those (5) of the second panel (2).